

Correction to: Transient Liquid Phase Bonding



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Correction to:
Chapter 9 in: K. S. Siow (ed.),
Die-Attach Materials for High Temperature Applications
in Microelectronics Packaging,
https://doi.org/10.1007/978-3-319-99256-3_9

The original version of the book was inadvertently published with an incorrect phrase stating “Need more here. Combine with above?” in Page 237 under Section 8.1.3 Au-In. This phrase has been corrected to show “At low temperatures, Au-In forms seven IMC phases between Au and In, with AuIn₂, AuIn, and Au₇In₃ observed in the reaction zone between Au and In even at the shortest reaction times [84].”

The updated online version of this chapter can be found at
https://doi.org/10.1007/978-3-319-99256-3_9

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K. S. Siow (ed.), *Die-Attach Materials for High Temperature Applications*
in Microelectronics Packaging, https://doi.org/10.1007/978-3-319-99256-3_11

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